CLAIMS

What is claimed:

1. An electronic package, comprising:

a substrate having first and second portions and a fold portion between the first and second portions;

a first microelectronic die mounted to the first portion; and

at least a first fold-controlling member, the fold portion being wrapped partially around the first fold-controlling member to place the second portion over the first portion.

2. The electronic package of claim 1, wherein the first fold-controlling member is a portion of a first mold cap over the first microelectronic die.

3. The electronic package of claim 2, further comprising an adhesive layer on the mold cap, the second portion being attached to the adhesive layer.

4. The electronic package of claim 1, wherein the surface of the first fold-controlling member around which the fold portion is wrapped is curved.

5. The electronic package of claim 4, wherein the surface is curved from the first portion up to the second portion.

6. The electronic package of claim 1, wherein the first fold-controlling member is a portion on a first mold cap over the first microelectronic die, the surface of the first fold-controlling member around which the fold portion is wrapped is curved from the first portion up to the second portion, further comprising an adhesive layer on the mold cap, the second portion being attached to the adhesive layer.

7. The electronic package of claim 1, further comprising a second microelectronic die mounted to the second portion.

8. The electronic package of claim 7, further comprising at least a second fold-controlling member, the fold portion being wrapped partially around the second fold-controlling member to place the second portion over the second portion.

9. The electronic package of claim 8, wherein the first and second fold-controlling members are attached to the first and second portions, respectively, before the fold portion is wrapped around the fold-controlling portions.

10. The electronic package of claim 9, wherein the second fold-controlling member is a portion of a second mold cap over the second microelectronic die.

11. The electronic package of claim 10, further comprising an adhesive layer on the first mold cap, the second mold cap being attached to the adhesive layer.

12. The electronic package of claim 7, further comprising a second microelectronic die mounted to the second portion, wherein the first fold-controlling member is a portion on a first mold cap over the first microelectronic die, wherein the second fold-controlling member is a portion or a second mold cap over the first microelectronic die, further comprising an adhesive layer on the first mold cap, the second mold cap being attached to the adhesive layer.

13. An electronic package, comprising:

a substrate having first and second portions and a fold portion between the first and second portions;

a microelectronic die mounted to the first portion;

a mold cap over the microelectronic die and attached to the first portion, the mold cap having a curved surface at an edge thereof, the fold portion being wrapped partially around the mold cap and substantially conforming to a shape of the curved surface, to place the second portion over the first portion.

14. The electronic package of claim 13, further comprising an adhesive layer on the mold cap, the second portion being attached to the adhesive layer.

15. The electronic package of claim 14, wherein the second portion is attached directly to the adhesive layer.

16. An electronic package, comprising:

a substrate having first and second portions and a fold portion between the first and second portions;

a first microelectronic die mounted to the first portion;

a second microelectronic die mounted to the second portion;

a first mold cap over the first microelectronic die and attached to the first portion, the first mold cap having a first curved surface at an edge thereof;

a second mold cap over the second microelectronic die and attached to the second portion, the second mold cap having a second curved surface at an edge thereof, the fold portion being partially wrapped around the first curved surface and partially around the second curved surface to place the second portion over the first portion.

17. The electronic package of claim 16, further comprising an adhesive layer on the first mold cap, the second mold cap being attached to the adhesive layer.

18. The electronic package of claim 16, wherein the first and second curved surfaces jointly form a continuous curvature from the first portion to the second portion.

19. A method of constructing an electronic package, comprising:

mounting a first microelectronic die to a first portion of a substrate having a fold portion next to the first portion and a second portion next to the fold portion;

positioning a fold-controlling member over the substrate;

wrapping a fold portion of the substrate partially around a surface of the fold-controlling portion to place the second portion over the first portion.

20. The method of claim 19, wherein the first fold-controlling member is a portion on a first mold cap over the first microelectronic die.

21. The method of claim 20, further comprising adhering the second portion to the mold cap.

22. The method of claim 19, wherein the surface of the first fold-controlling member around which the fold portion is wrapped is curved.

23. The method of claim 19, wherein the fold-controlling member is injection-molded.

24. The method of claim 23, further comprising:

locating a shape-defining piece on the substrate, the fold-controlling member being molded against a surface of the shape-defining piece; and

removing the shape-defining piece.

25. The method of claim 24, wherein contacting surfaces of the shape-defining piece and fold-controlling member are concave and converse, respectively.